Product Change Notification

PCN No:	Chipcon Product Name:	
PCN_CC2420_001	CC2420	
Data sheet reference: **No data sheet parameters are affected. Notice separate solder profile for lead free soldering.**	**Customer reference:** NA	**Date:** 2005-01-21

Description of change:

The affected Chipcon device will change from SnPb (tin/lead) plating to matte-tin (Sn) plating on the device leads. The base lead frame material (copper) is not changing, only the final plating material.
The device has been qualified to meet the Pb-free soldering temperatures required by Pb-free solder reflow processes and can use Pb-free soldering paste such as Sn/Ag/Cu. Ref. data sheet for each individual product.
This new matte tin finish is also backward compatible with existing SnPb soldering and can use standard SnPb soldering paste.

During a transition period customers may receive parts with either SnPb or Sn-only plating, due to existing inventory of SnPb-plated product.

Reason for change:

New regulations being imposed in Europe (RoHS) and some Asian countries necessitate the elimination of lead (Pb) in electronics manufacturing processes. The conversion from SnPb finish to matte-tin plating on the device leads is being implemented to meet these new requirements.
The electronic component industry worldwide is affected and will begin using Pb-free plating compound soon. Many manufacturers will use matte-tin plating similar to that chosen by Chipcon.
Matte tin was chosen above other plating materials due to its backward- and forward-compatibility with both SnPb and Pb-free solder reflow processes and its similar cost structure to SnPb plating.

Consequence of change:

No change in electrical performance. I.e. same data sheet parameters as before. For “lead free” parts the soldering profile needs to be changed in order to meet the requirements for lead free soldering. The soldering profile is in accordance with JEDEC J-STD-020B. For more information, please consult datasheet rev. 1.3, to be released.

Verification:

First Article Inspection has been performed by Chipcon to verify that the electrical performance is in accordance with the product data sheet. The RoHS compatible packages are qualified by Chipcon’s subcontractors.

Change active from (date):	Change active from (date code & lot code):
Transition estimated during Q2/Q3-2005	To be published on Chipcon’s home page.
Last time order (date): **NA**	**Last shipment date:** **NA**
Approval / Date : **ARK / 2004-11-30**	**Signature :** **Arne Kjensmo, VP Operations**